STL26NM60N

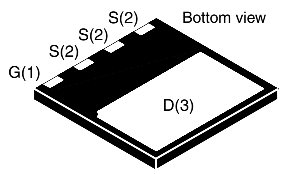
N-channel 600 V, 0.160 Ω, 19 A PowerFLAT™ 8x8 HV ultra low gate charge MDmesh™ II Power MOSFET

Features

Order code	V_{DSS} @ T_{Jmax}	$R_{DS(on)}$ max	I_D
STL26NM60N	650 V	< 0.185 Ω	19 A (1)

1. The value is rated according to $R_{thj\text{-}case}$

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance



PowerFLAT™ 8x8 HV

Applications

- Switching applications

Description

This device is an N-channel MDmesh™ V Power MOSFET based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low on-resistance, which is unmatched among silicon-based Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

Figure 1. Internal schematic diagram

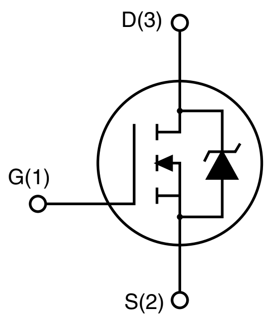


Table 1. Device summary

Order code	Marking	Package	Packaging
STL26NM60N	26NM60N	PowerFLAT™ 8x8 HV	Tape and reel

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0)	600	V
V_{GS}	Gate-source voltage	± 25	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	19	A
I_D (1)	Drain current (continuous) at T_C = 100 °C	12	A
I_D(2)	Drain current (continuous) at T_{amb} = 25 °C	2.7	A
I_D(2)	Drain current (continuous) at T_{amb} = 100 °C	1.7	A
I_{DM}(2),(3)	Drain current (pulsed)	10.8	A
P_{TOT} (2)	Total dissipation at T_{amb} = 25 °C	3	W
P_{TOT}(1)	Total dissipation at T_C = 25 °C	125	W
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max)	7.5	A
E_{AS}	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	400	mJ
dv/dt (3)	Peak diode recovery voltage slope	15	V/ns
T_{stg}	Storage temperature	- 55 to 150	°C
T_j	Max. operating junction temperature	150	°C

1. The value is rated according to $R_{thj\text{-}case}$
2. When mounted on FR-4 board of inch², 2oz Cu
3. I_{SD} ≤ 19 A, di/dt ≤ 400 A/µs, $V_{DS\ peak} \leq V_{(BR)DSS}$, V_{DD} = 80% $V_{(BR)DSS}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case max	0.83	°C/W
$R_{thj\text{-}amb}$(1)	Thermal resistance junction-amb max	45	°C/W

1. When mounted on 1inch² FR-4 board, 2 oz Cu

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0	600			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 600 V V_{DS} =600 V, T_C=125 °C			1 100	µA µA
I_{GSS}	Gate-body leakage current (V_{DS} = 0)	V_{GS} = ± 25 V			100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS} = 10 V, I_D = 10 A		0.160	0.185	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0	-	1800 115 1.1	-	pF pF pF
$C_{oss(eq)}$ (1)	Equivalent capacitance time related	V_{DS} = 0 to 480 V, V_{GS} = 0	-	310	-	pF
R_G	Intrinsic gate resistance	f = 1 MHz open drain	-	2.8	-	Ω
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 480 V, I_D = 19 A, V_{GS} = 10 V (see *Figure 14*)	-	60 8.5 30	-	nC nC nC

1. $C_{oss\ eq.}$ time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 300 V, I_D = 10 A, R_G = 4.7 Ω, V_{GS} = 10 V (see *Figure 15*), (see *Figure 18*)	-	13 25 85 50	-	ns ns ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM} (1)	Source-drain current Source-drain current (pulsed)		-		19 76	A A
V_{SD} (2)	Forward on voltage	I_{SD} = 19 A, V_{GS} = 0	-		1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 19 A, di/dt = 100 A/µs V_{DD} = 100 V (see *Figure 15*)	-	370 5.8 31.5		ns µC A
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 19 A, di/dt = 100 A/µs V_{DD} = 100 V, T_j = 150 °C (see *Figure 15*)	-	450 7.5 32.5		ns µC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

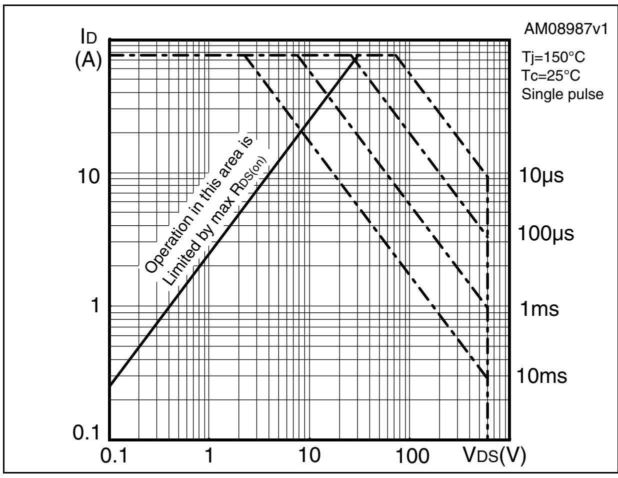


Figure 3. Thermal impedance

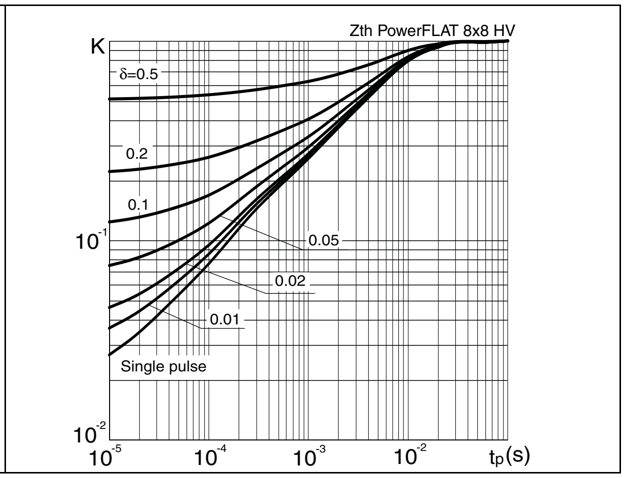


Figure 4. Output characteristics

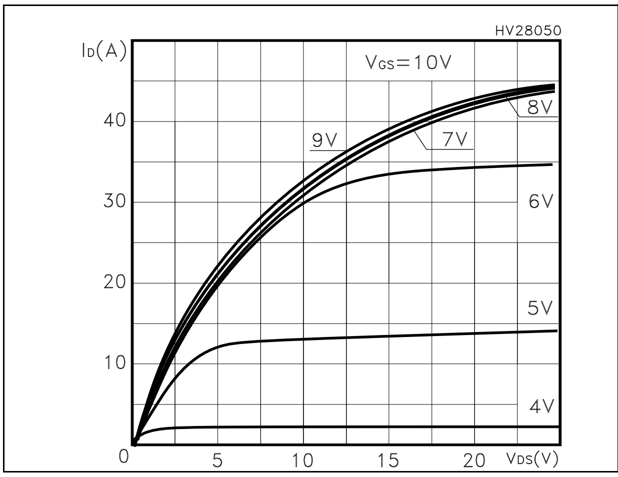


Figure 5. Transfer characteristics

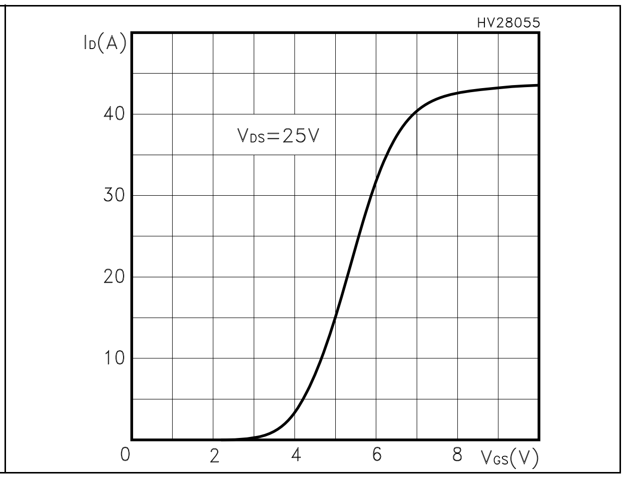


Figure 6. Normalized V_{DS} vs temperature

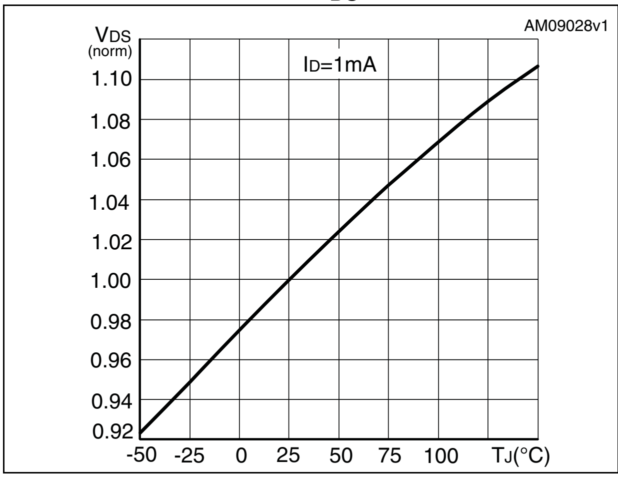


Figure 7. Static drain-source on resistance

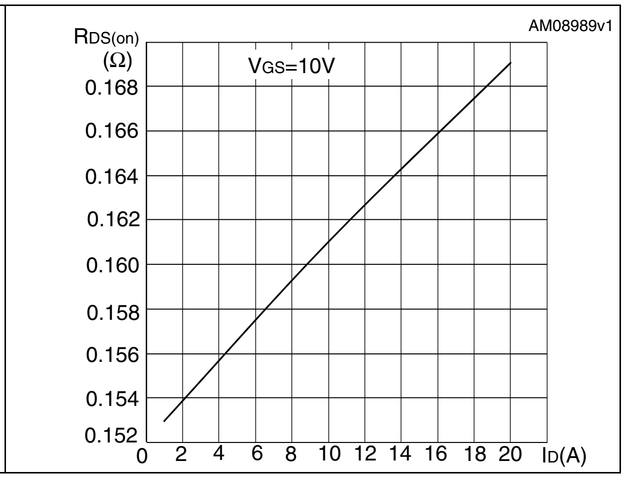


Figure 8. Gate charge vs gate-source voltage

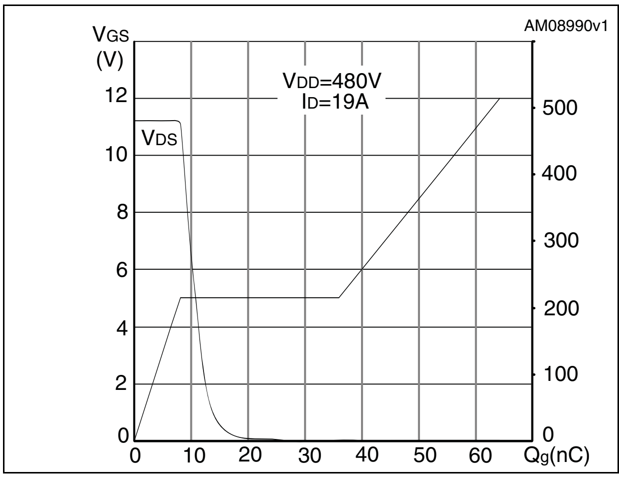


Figure 9. Capacitance variations

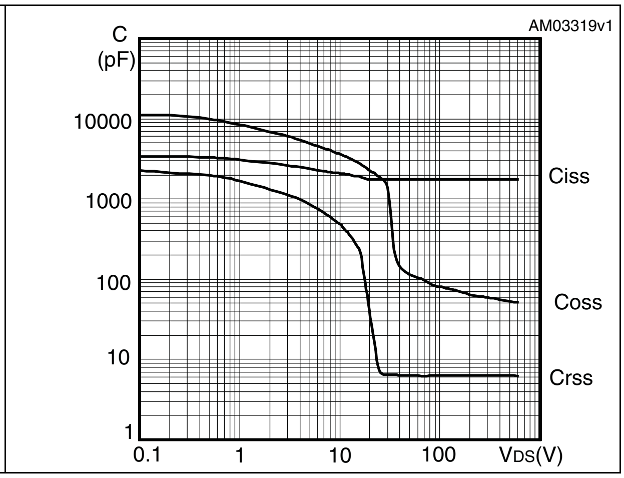


Figure 10. Normalized gate threshold voltage vs temperature

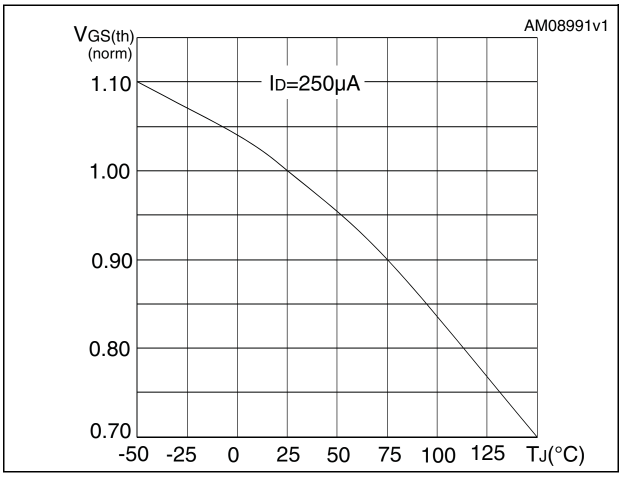


Figure 11. Normalized on resistance vs temperature

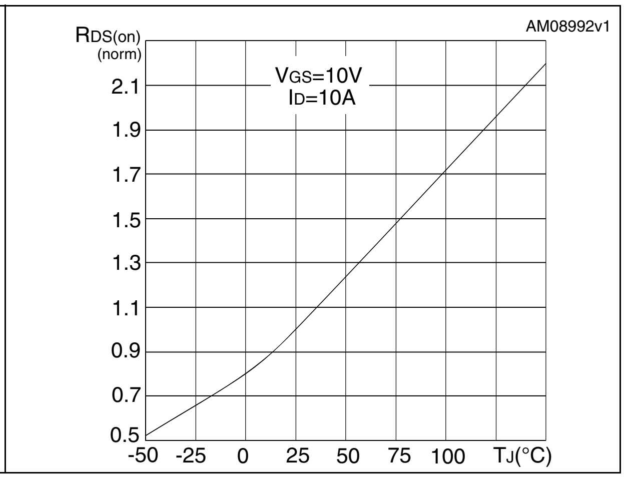
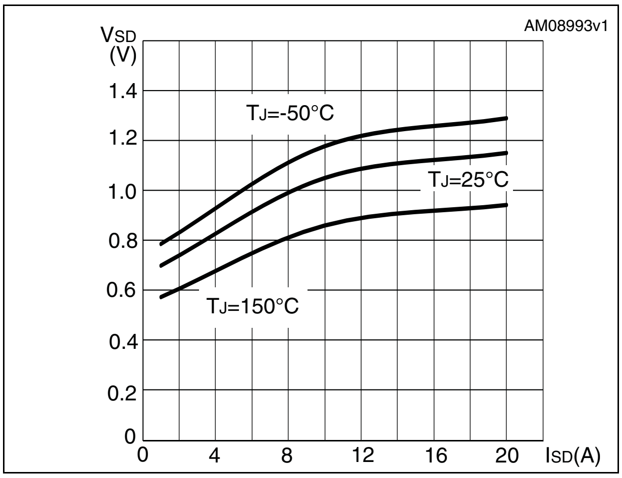


Figure 12. Source-drain diode forward characteristics



3 Test circuits

Figure 13. Switching times test circuit for resistive load

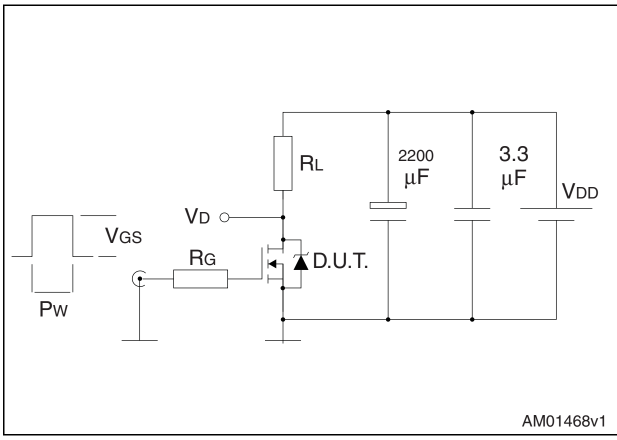


Figure 14. Gate charge test circuit

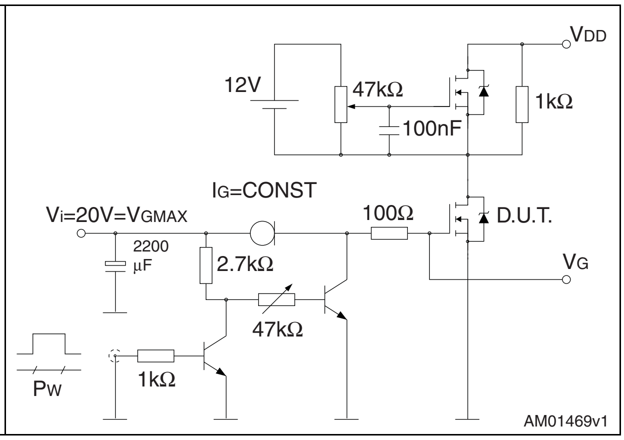


Figure 15. Test circuit for inductive load switching and diode recovery times

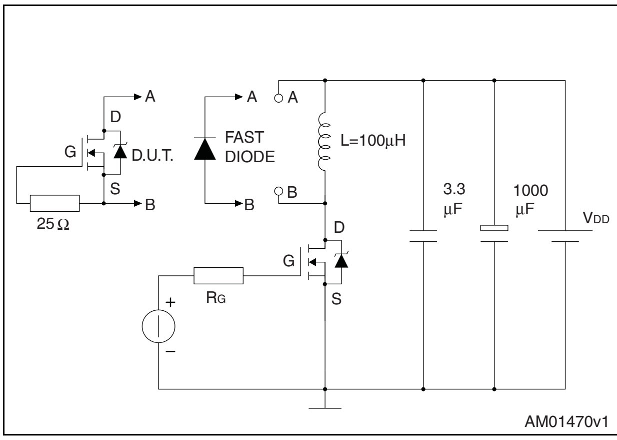


Figure 16. Unclamped inductive load test circuit

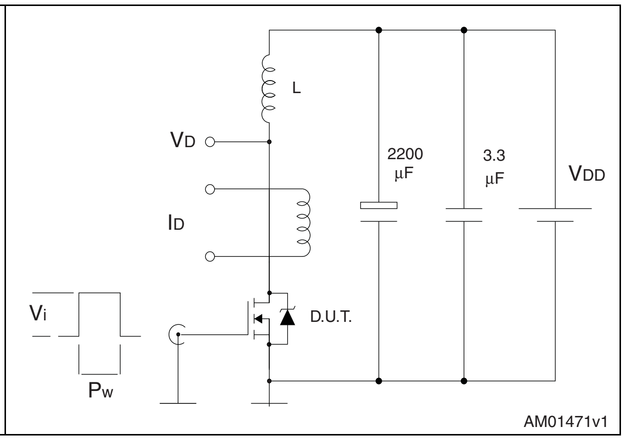


Figure 17. Unclamped inductive waveform

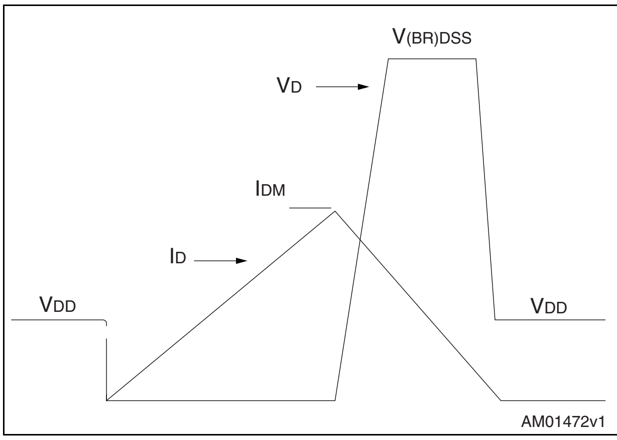
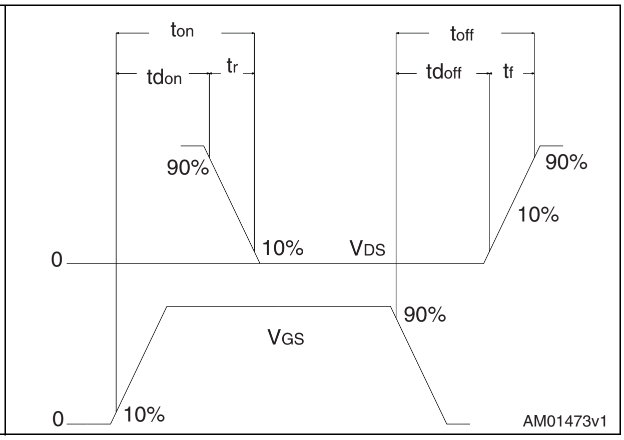


Figure 18. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. PowerFLAT™ 8x8 HV mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
b	0.95	1.00	1.05
D		8.00	
E		8.00	
D2	7.05	7.20	7.30
E2	4.15	4.30	4.40
e		2.00	
L	0.40	0.50	0.60
aaa		0.10	
bbb		0.10	
ccc		0.10	

Figure 19. PowerFLAT™ 8x8 HV drawing mechanical data

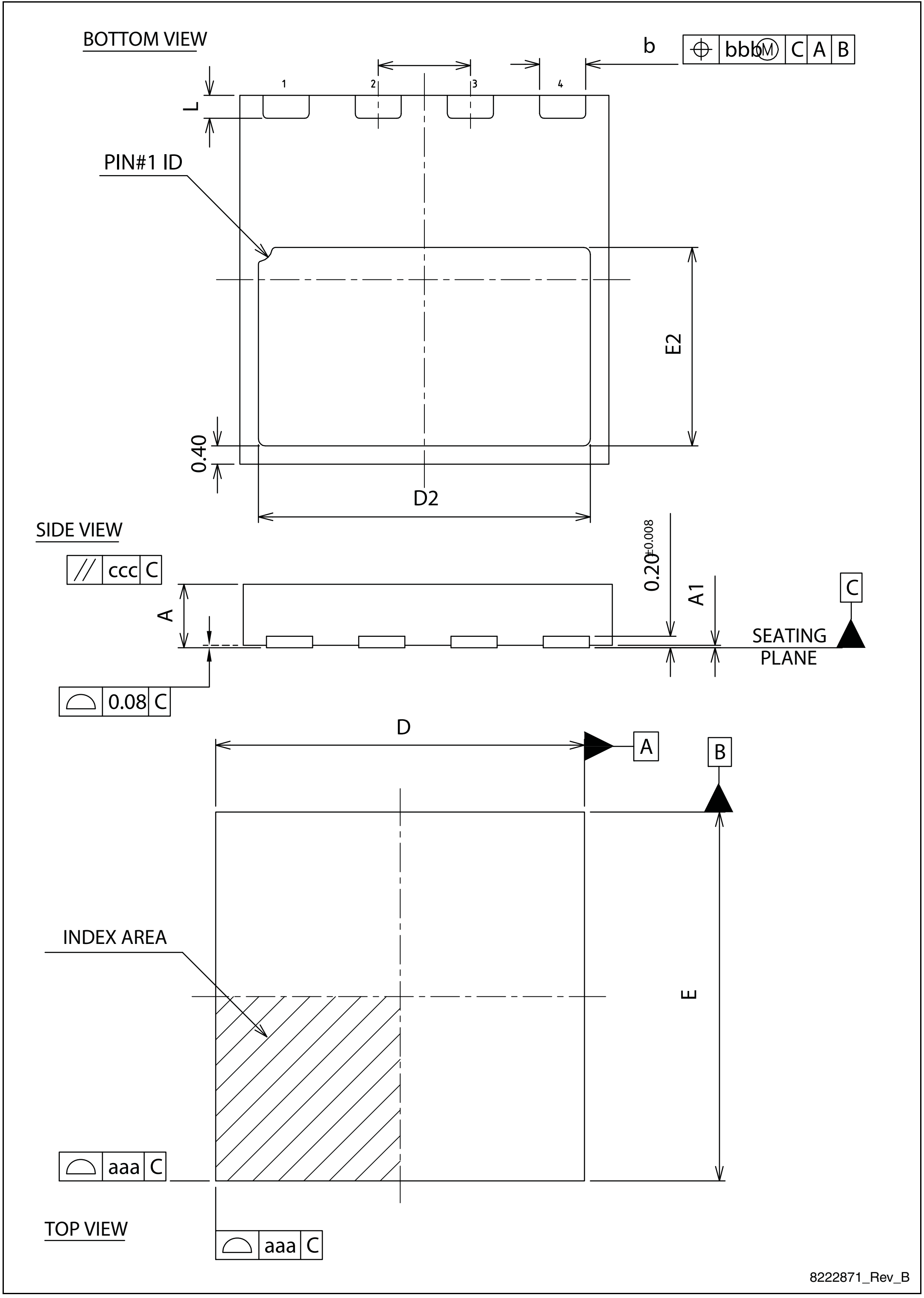
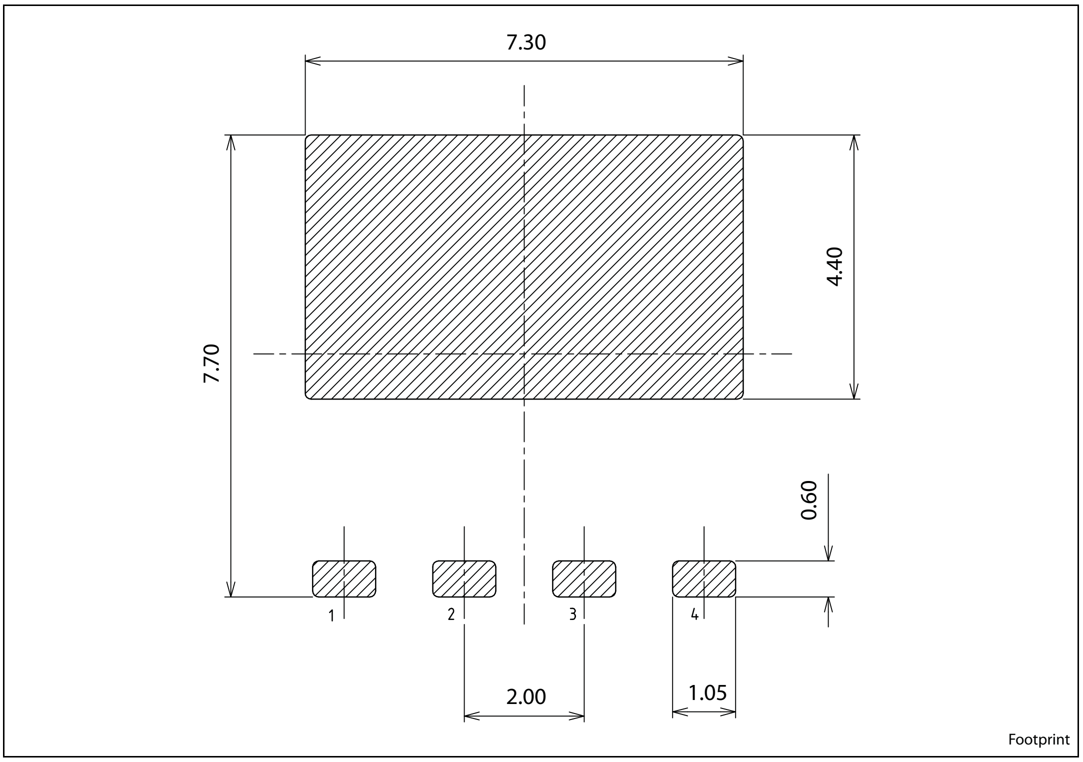


Figure 20. PowerFLAT™ 8x8 HV recommended footprint



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
14-Feb-2011	1	First release.
03-Nov-2011	2	*Section 4: Package mechanical data* has been updated. Minor text changes.